

FIG.1

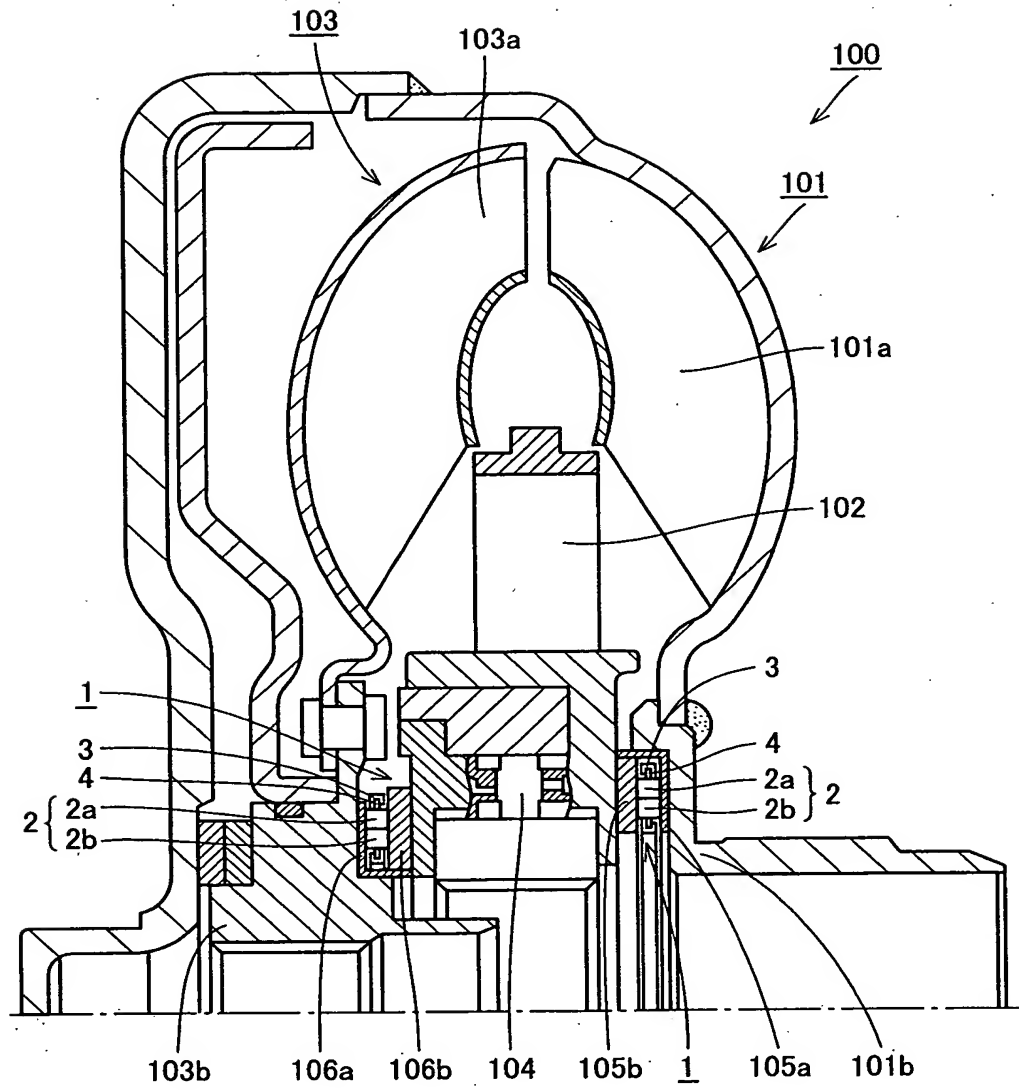


FIG.2A

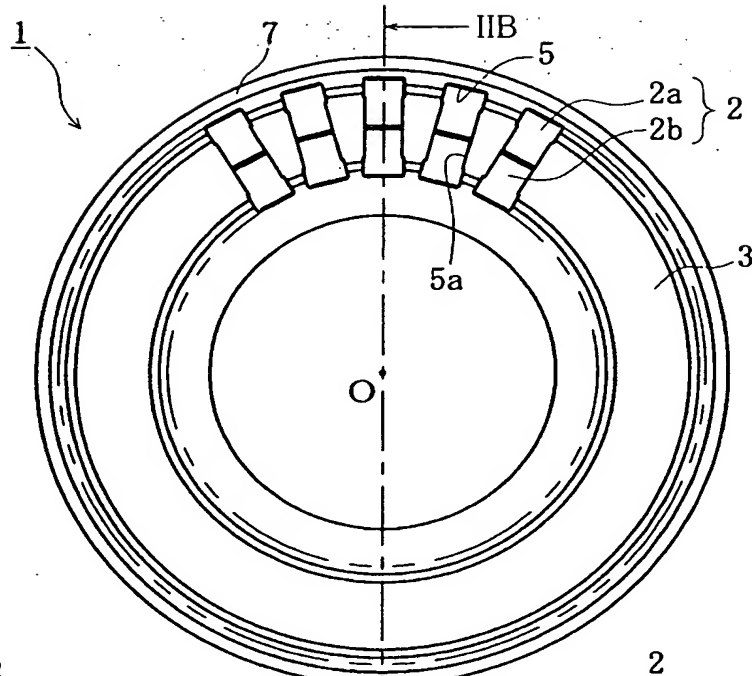


FIG.2B

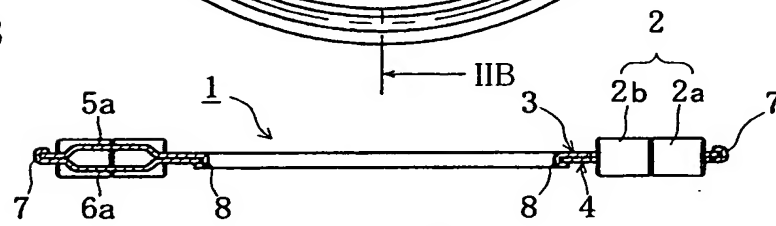


FIG.2C

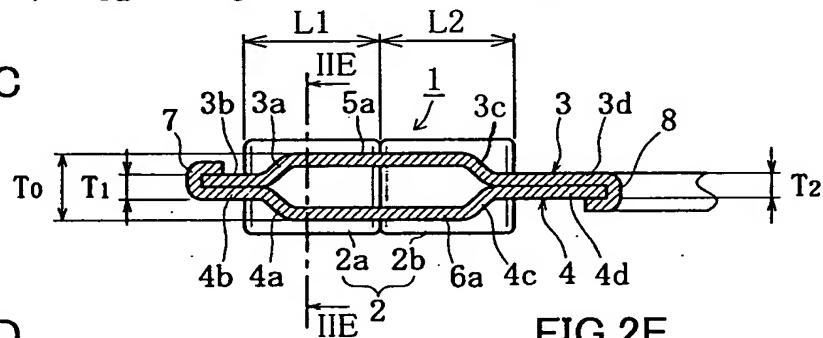


FIG.2D

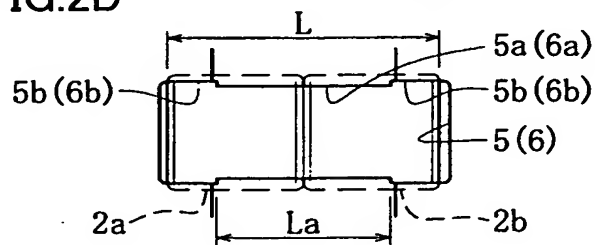


FIG.2E

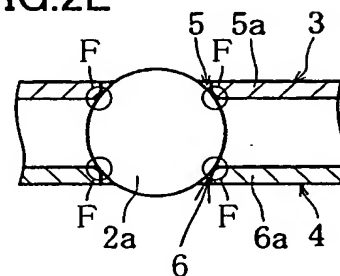


FIG.3

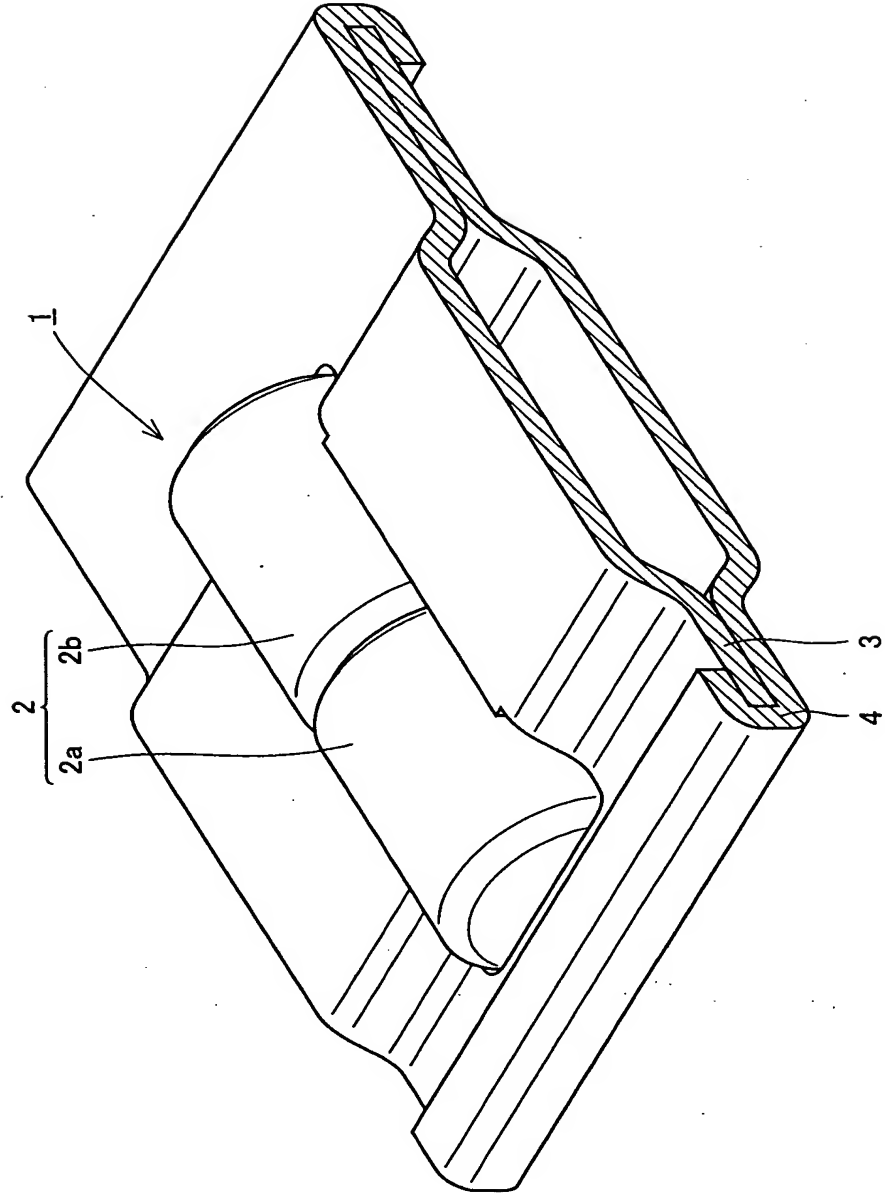


FIG.4

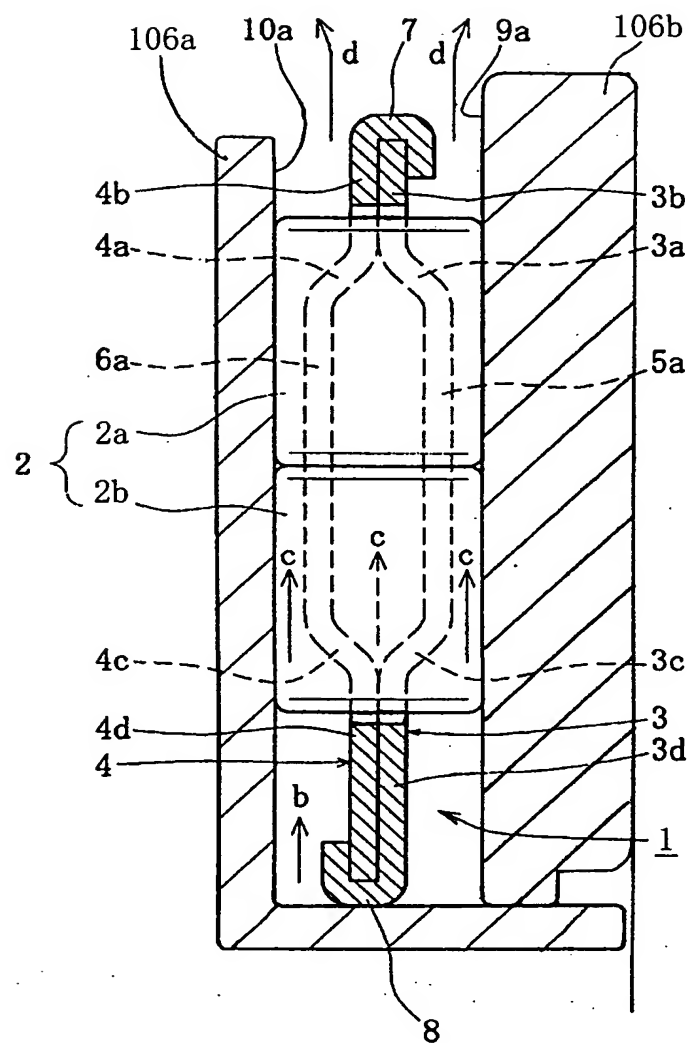


FIG.5

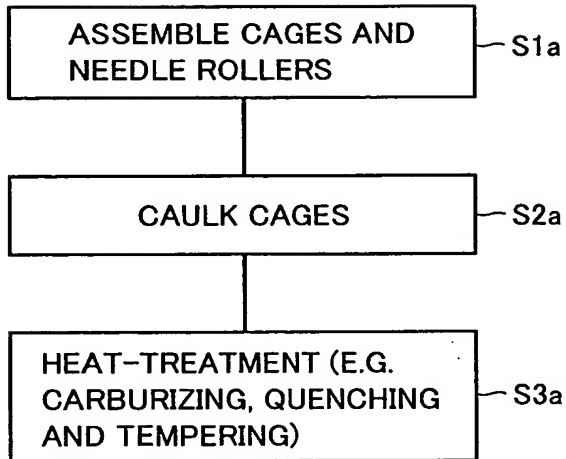


FIG.6

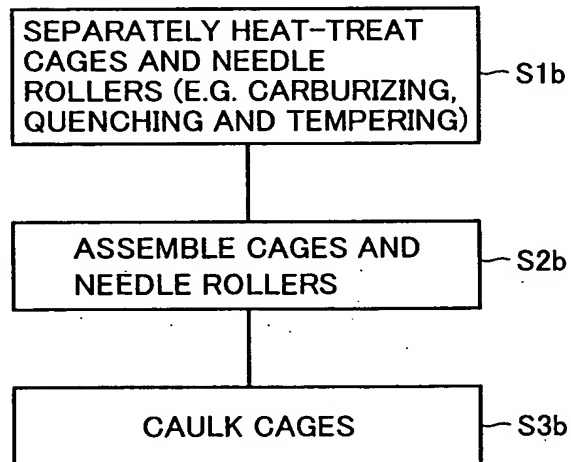


FIG.7A

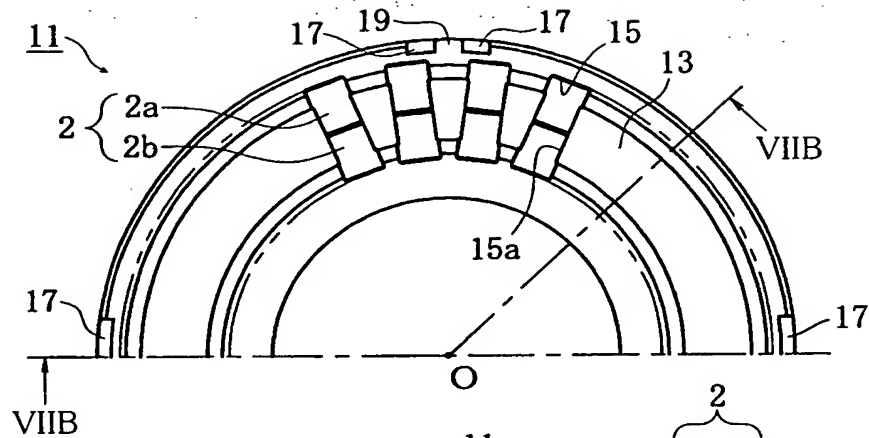


FIG.7B

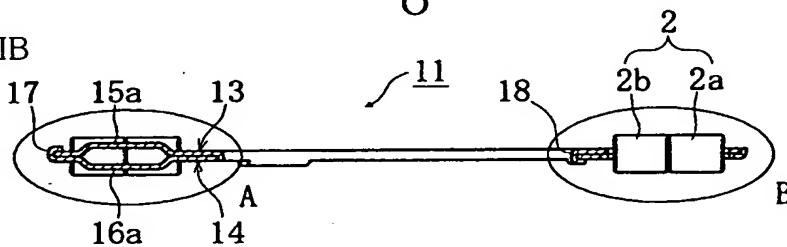


FIG.7C

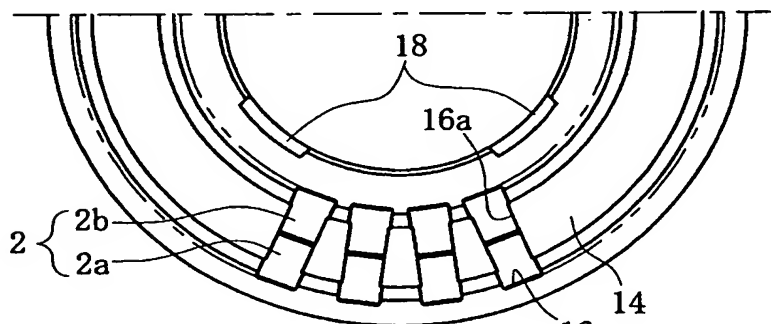


FIG.7D

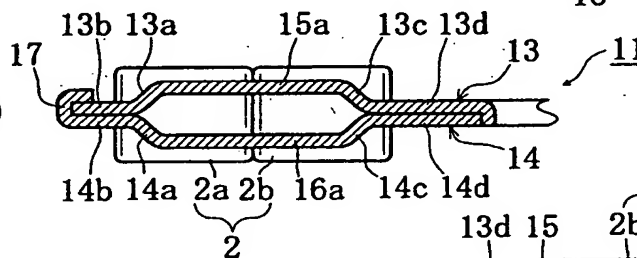


FIG.7E

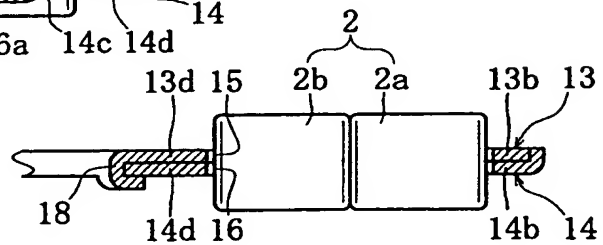


FIG.8A

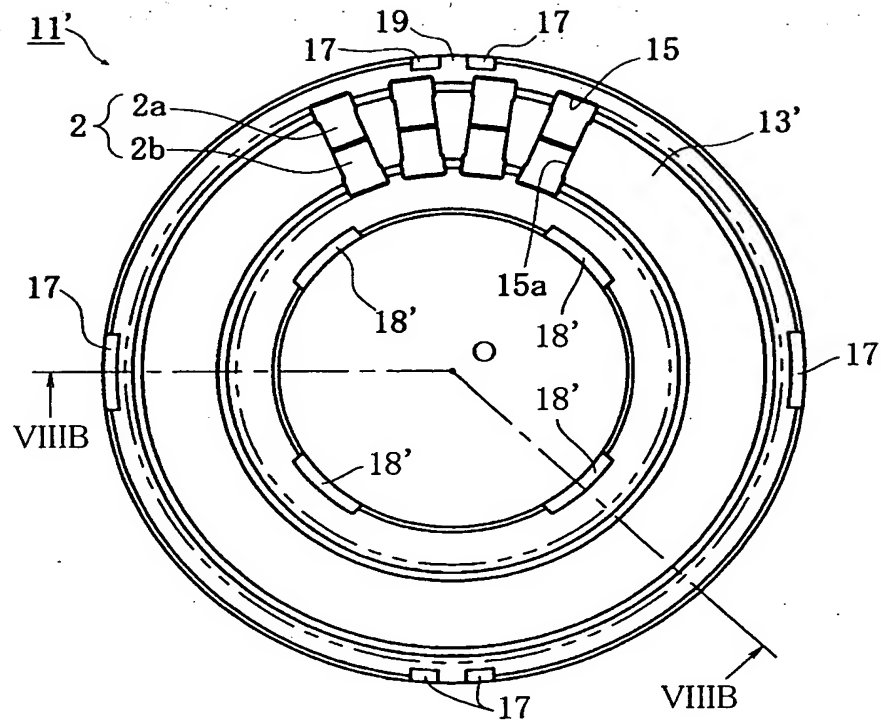


FIG.8B

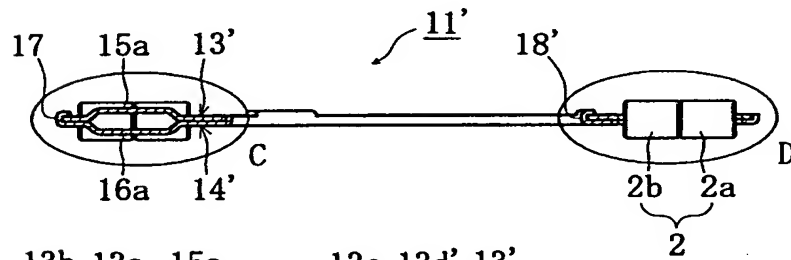


FIG.8C

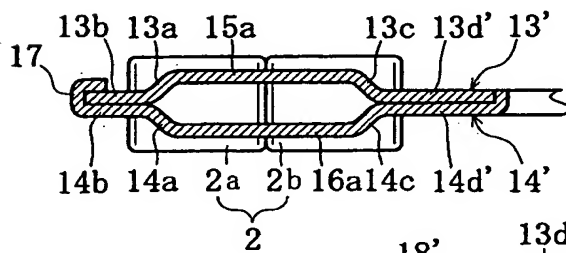


FIG.8D

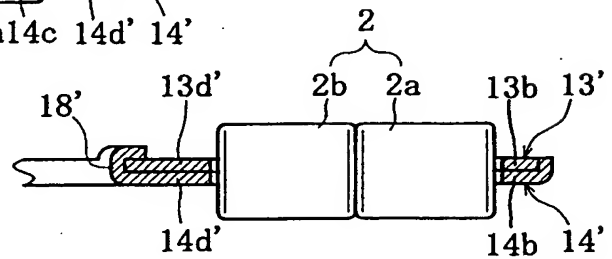


FIG.9A

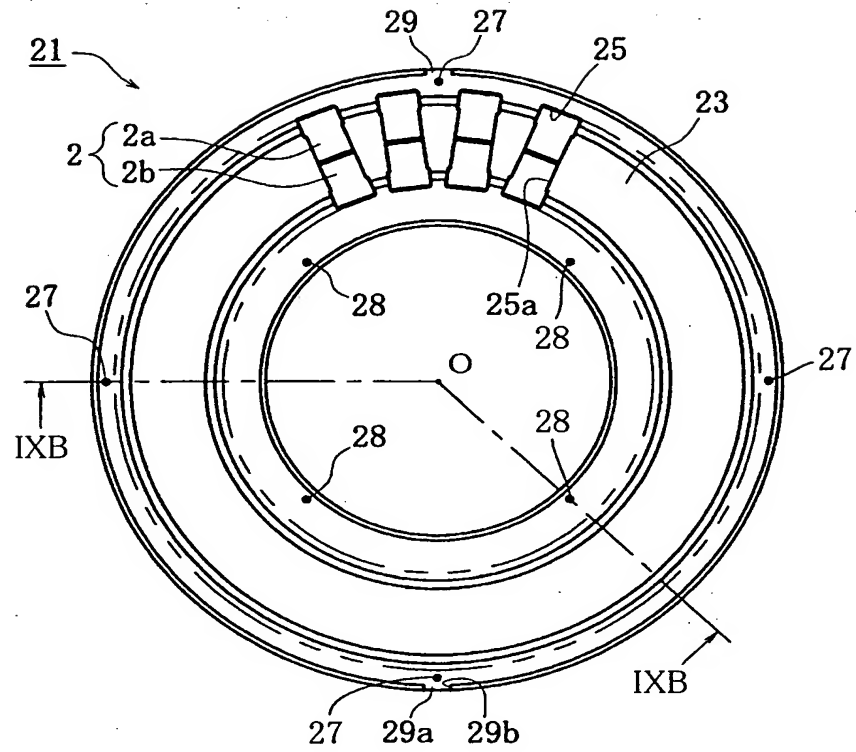


FIG.9B

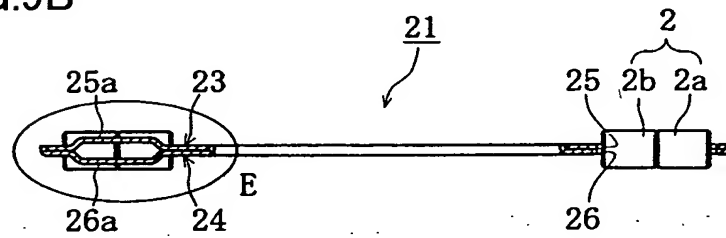


FIG.9C

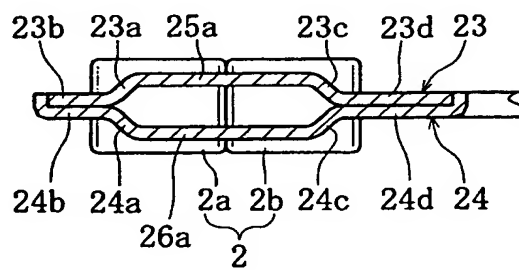




FIG.10

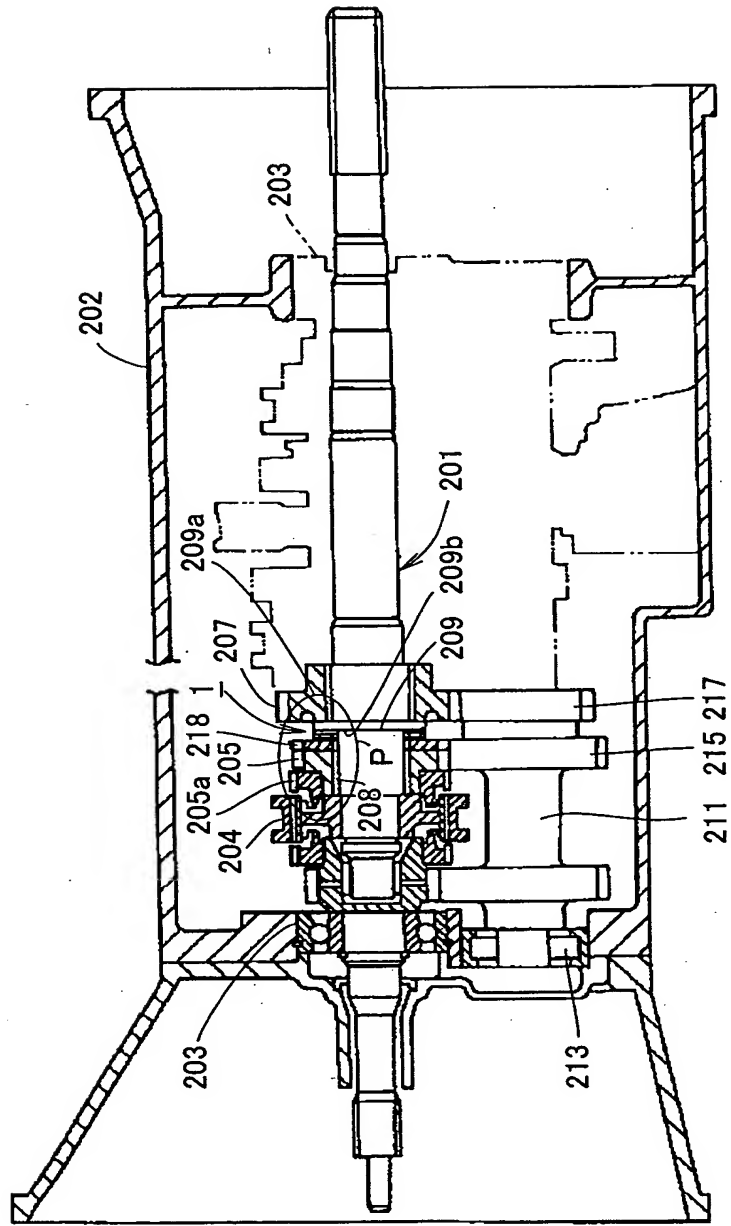


FIG.11

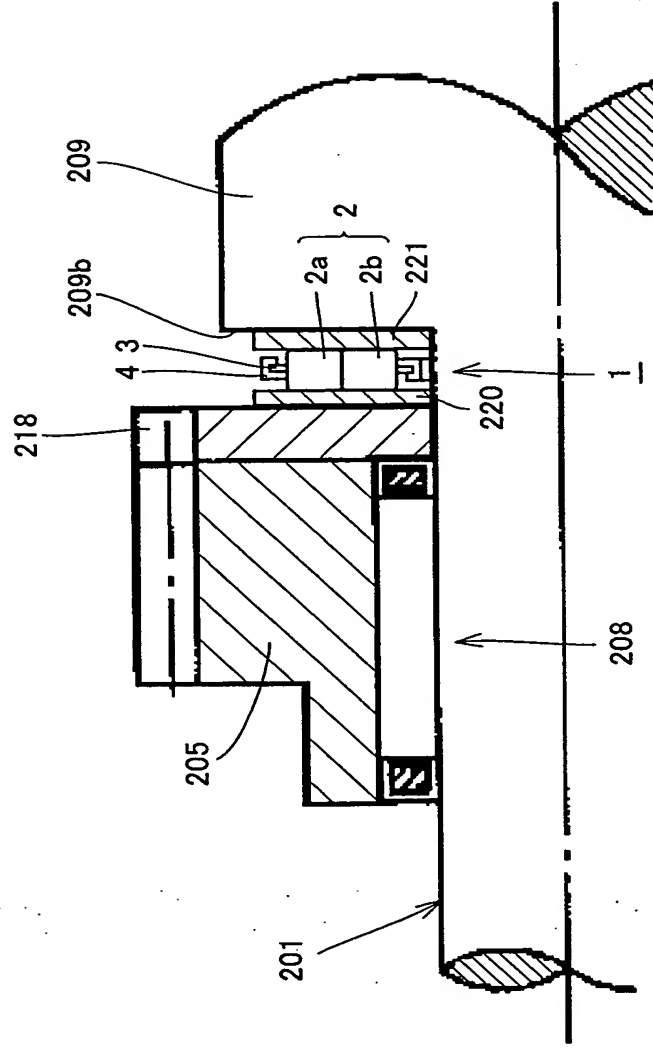


FIG.12A

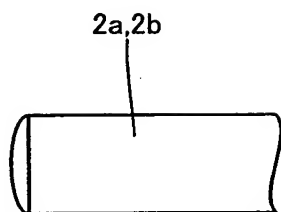
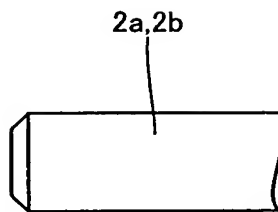


FIG.12B



This technical drawing illustrates a complex multi-layered electronic assembly in cross-section. The central component is a core (300) encased within several structural layers: an inner layer (301), a middle layer (302), an outer layer (303), and a base layer (304). A protective coating (305) covers the bottom surface. The top and bottom surfaces feature intricate interconnect structures. The top surface (306) includes components like 311, 312, 313, 315, and 316, which are linked by conductive traces (312a, 313a, 314a, 314b). Similarly, the bottom surface (307) has corresponding components (308, 309, 310, 311, 312, 313, 315, 316) and connecting paths. Various other parts are labeled with numerals such as 301a, 301b, 302a, 302b, 303a, 303b, 304a, 304b, 305a, 305b, 306a, 306b, 307a, 307b, 308a, 308b, 309a, 309b, 310a, 310b, 311a, 311b, 312a, 312b, 313a, 313b, 314a, 314b, 315a, 315b, 316a, and 316b.

FIG.14

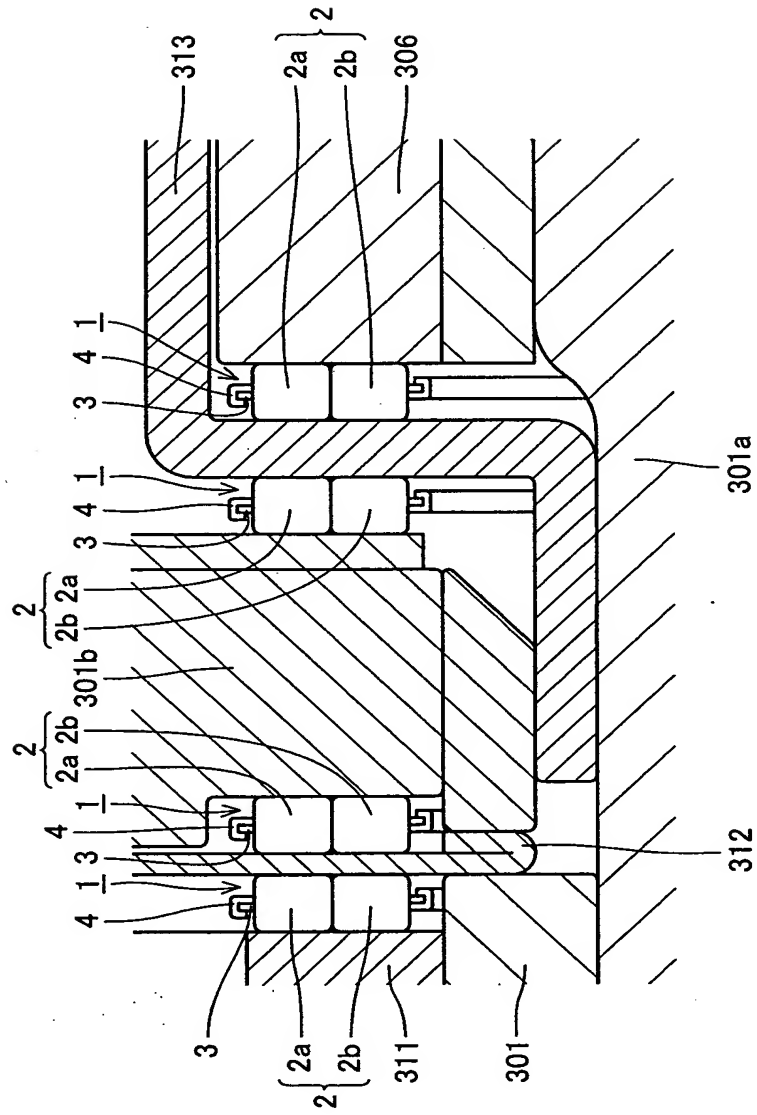


FIG.15

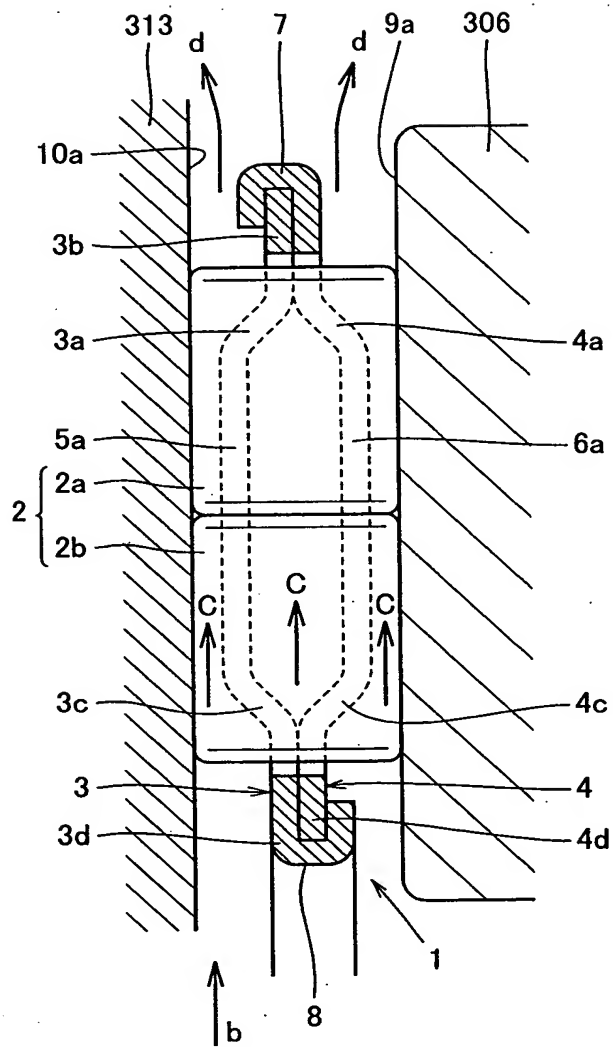


FIG.16A

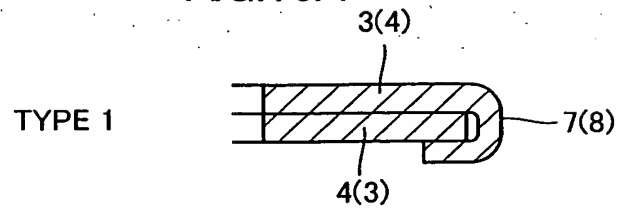


FIG.16B

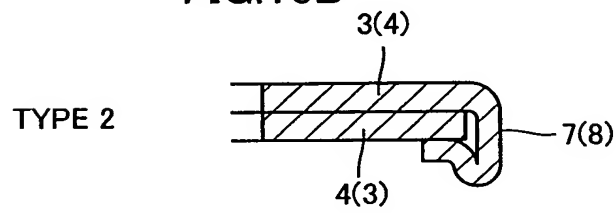


FIG.16C

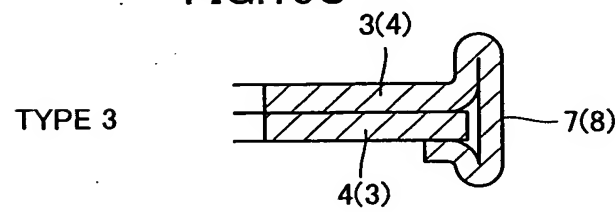


FIG.16D

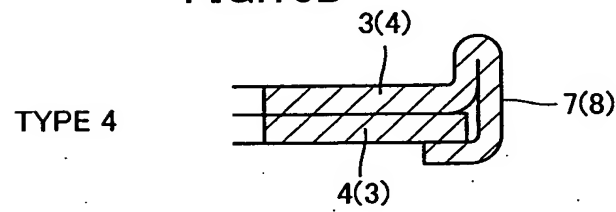


FIG.16E

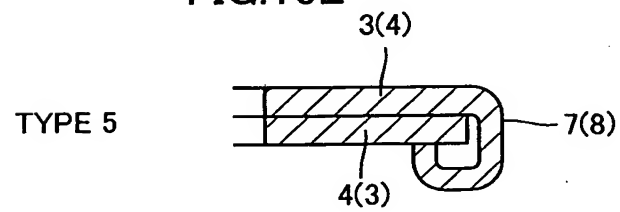


FIG.17A PRIOR ART

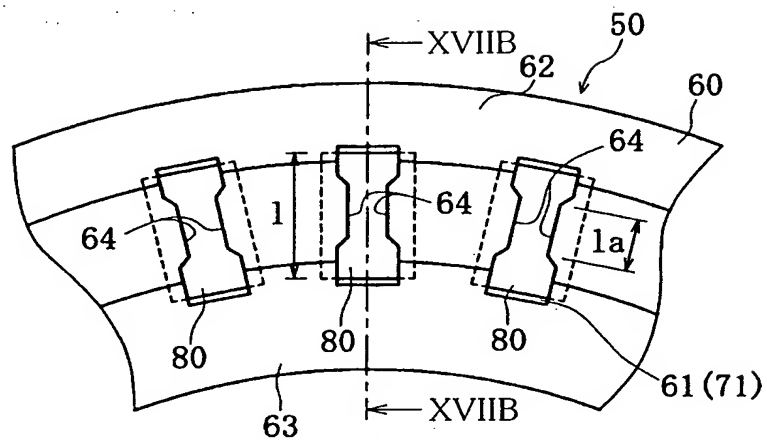


FIG.17B PRIOR ART

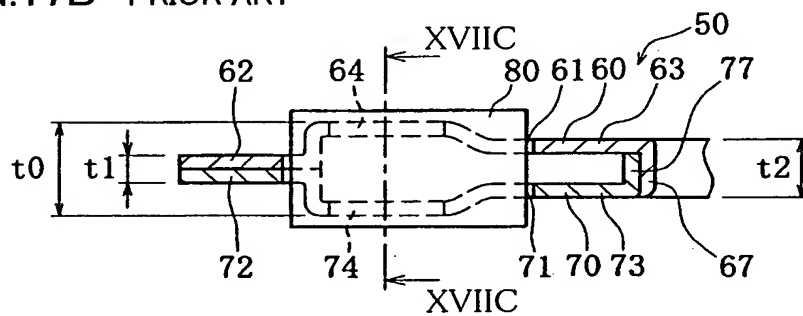


FIG.17C PRIOR ART

